

## Features

- Fast Switching Speed
- Low Forward Voltage: Maximum of 0.715V at 1mA
- Fast Reverse Recovery: Maximum of 4ns
- Low Capacitance: Maximum of 1.5pF
- Low Leakage Current: Maximum of 500nA at 80V
- Small Surface Mount Package
- Thermally Efficient Copper Alloy leadframe for High Power Dissipation
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

## Mechanical Data

- Case: SOD323F
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Copper Alloy leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 
- Weight: 0.003 grams (approximate)

SOD323F



Top View

## Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
1N4148WSF-7	Standard	JP	7	8	3,000/Tape & Reel

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



JP = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: A = 2013)  
 M = Month (ex: 9 = September)

### Date Code Key

Year	2013	2014	2015	2016	2017	2018	2019	2020				
Code	A	B	C	D	E	F	G	H				
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	$V_{RM}$	100	V
Peak Repetitive Reverse Voltage	$V_{RRM}$		
Working Peak Reverse Voltage	$V_{RWM}$	100	V
DC Blocking Voltage	$V_R$		
RMS Reverse Voltage	$V_{R(\text{RMS})}$	71	V
Forward Continuous Current (Note 5)	$I_{FM}$	250	mA
Non-Repetitive Peak Forward Surge Current	$I_{FSM}$ @ $t = 1.0\mu\text{s}$ @ $t = 1.0\text{ms}$ @ $t = 1.0\text{s}$	4.0 1.0 0.5	A

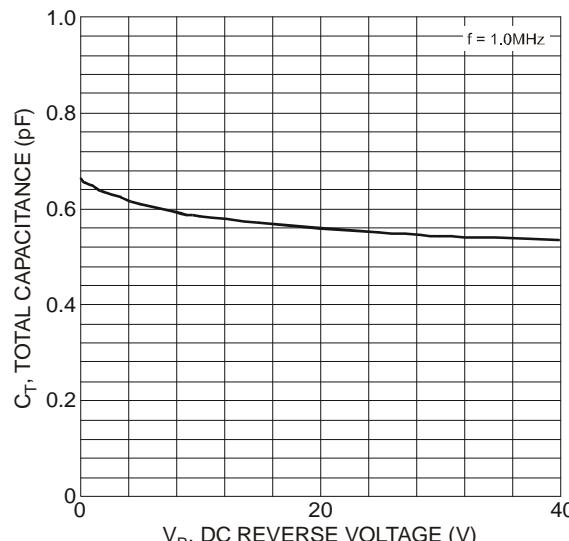
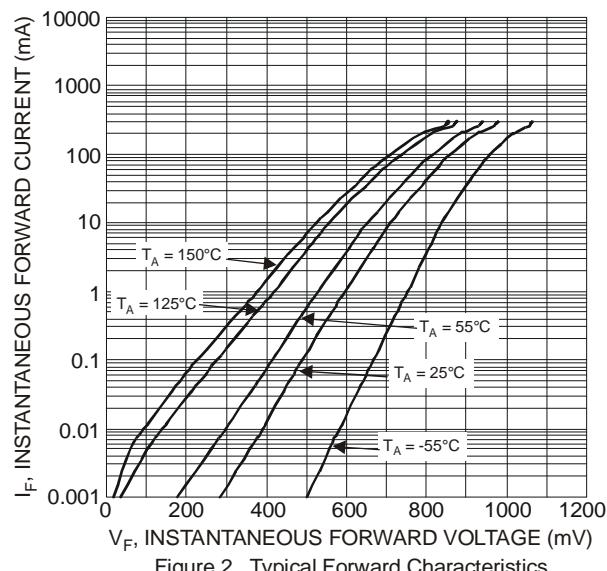
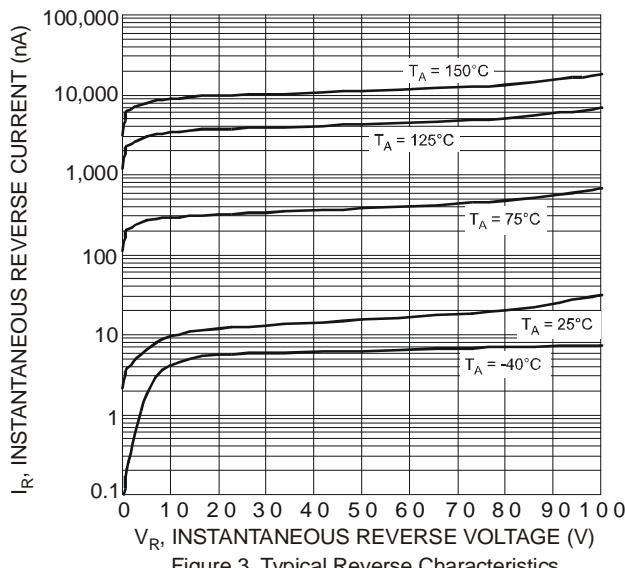
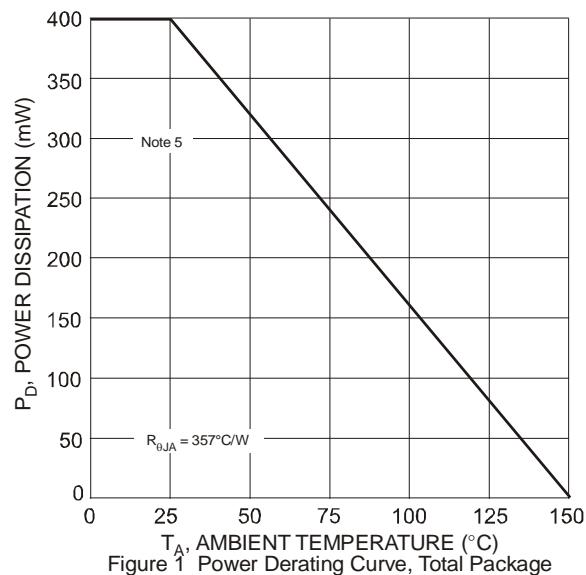
## Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	$P_D$	400	mW
Thermal Resistance Junction to Ambient Air (Note 5)	$R_{\theta JA}$	313	°C/W
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	°C

 Electrical Characteristics (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

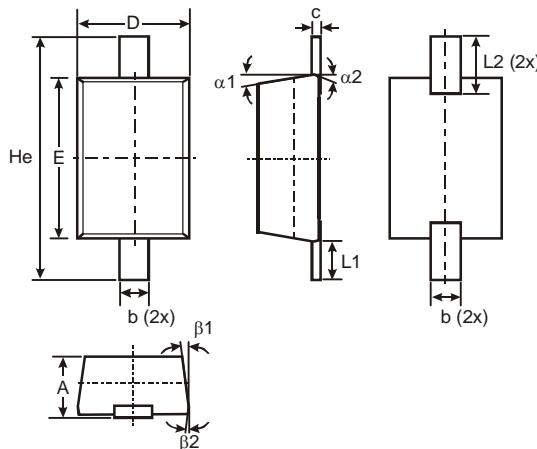
Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	100	—	V	$I_R = 100\mu\text{A}$
Forward Voltage	$V_F$	—	0.715 0.855 1.0 1.25	V	$I_F = 1.0\text{mA}$ $I_F = 10\text{mA}$ $I_F = 50\text{mA}$ $I_F = 150\text{mA}$
Leakage Current (Note 6)	$I_R$	—	0.5 50 30 30	$\mu\text{A}$ $\mu\text{A}$ $\mu\text{A}$ nA	$V_R = 80\text{V}$ $V_R = 80\text{V}, T_J = +150^\circ\text{C}$ $V_R = 25\text{V}, T_J = +150^\circ\text{C}$ $V_R = 25\text{V}$
Total Capacitance	$C_T$	—	1.5	pF	$V_R = 0, f = 1.0\text{MHz}$
Reverse Recovery Time	$t_{rr}$	—	4.0	ns	$I_F = I_R = 10\text{mA}$ , $I_{rr} = 0.1 \times I_R, R_L = 100\Omega$

Notes: 5. Device mounted on FR-4 PCB, on minimum recommended, 2oz copper pad layout.  
 6. Short duration pulse test used to minimize self-heating effect.



## Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.

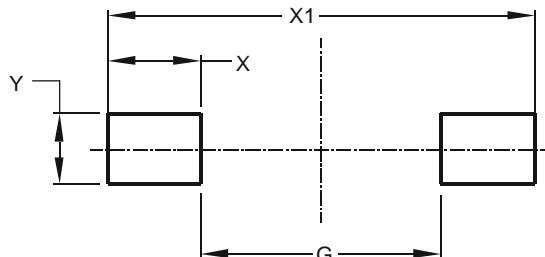


SOD323F			
Dim	Min	Max	Typ
A	0.60	0.75	—
b	0.25	0.35	—
c	0.05	0.26	—
D	1.15	1.35	1.25
E	1.60	1.80	1.70
He	2.30	2.70	2.50
L1	0.30	0.50	0.40
L2	0.41	0.61	0.51
α1	—	—	7°
α2	—	—	3°
β1	—	—	7°
β2	—	—	3°

All Dimensions in mm

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
G	1.280
X	0.710
X1	2.700
Y	0.403

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